



# Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP t5565z Thin Client

Name / Model #5

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm MB	1
Batteries	All types including standard alkaline and lithium coin or button style batteries MB	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		2
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		

Components, parts and materials containing radioactive substances		
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## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screw driver ( Used for M3 screw and M3.5 screw on Astronaut)	2# 2.55~3.45 Kgf.cm
Description #2	
Description #3	
Description #4	
Description #5	

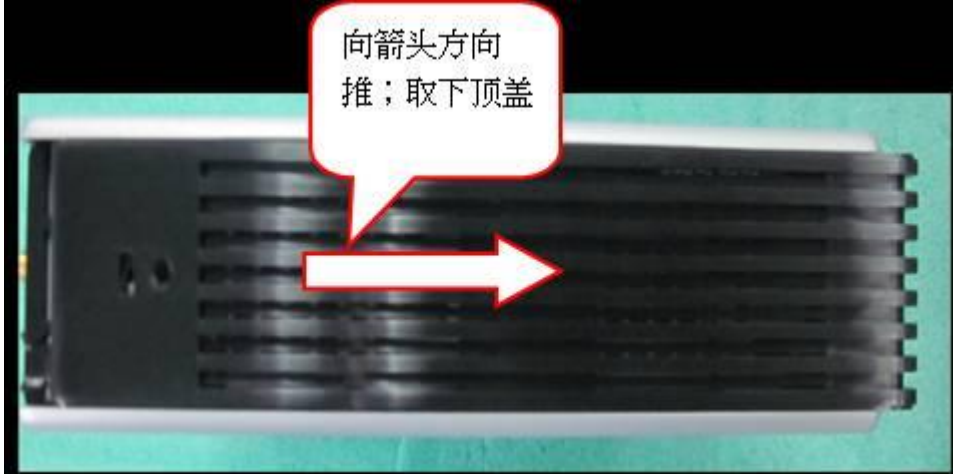
## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove one screw on top cover, and remove the top cover. pls refer to figure 1 in 3.2section.
2. Disassembling upper& bottom cover,pls refer to figure 2-1&2-2 in 4.2section.
3. Take 4pcs screws from metal plate, disassemble metal plate from chassis.pls refer to figure 3 in 5.2 section.
4. Remove 2pcs screws form WLAN card, pll out atenna for WLAN card.pls refer figure 4 in 5.2 section.
5. Firstly,remove nut form atenna connector,then disassemble gasket,catch the atenna.pls refer to figure 5 in 6.2 section.
6. To be Extract speaker cable form main board.pls refer to figure 6 in 6.2 section.
7. Unloading the 2pcs themal pad, use screwdriver remove 5pcs screws from main board.pls refer to figure 7 in 6.2 section.
8. Disassemble the main board and side cover from chassis.pls refer to figure 8 in 7.2 section.
9. Using screwdriver take 8pcs screws from side cover.pls refer to figure 9 in 7.2 section.
10. Disassemble DIMM from main board, then remove PATA.pls refer to figure 10 in7.2 section.
11. Disassembling ATA , then take off the stand-off.pls refer to figure 11 in8.2 section.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

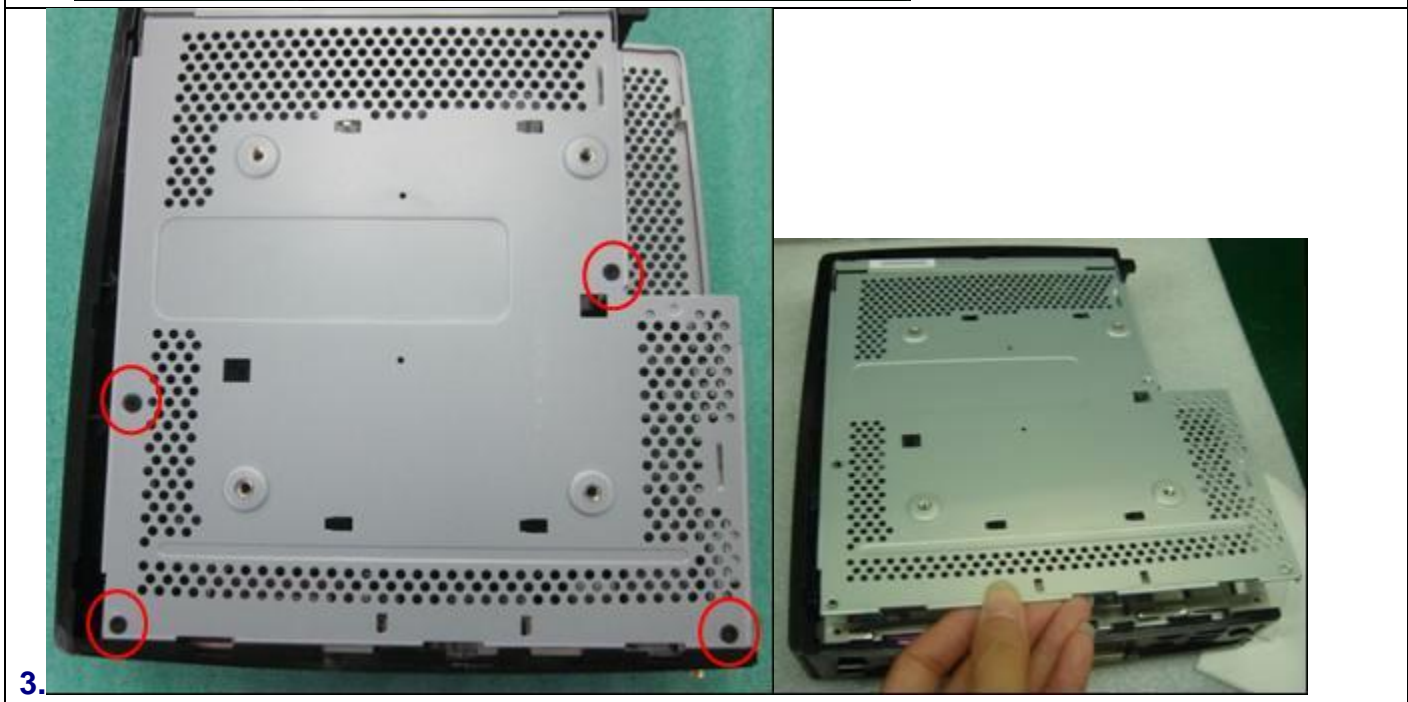
1.

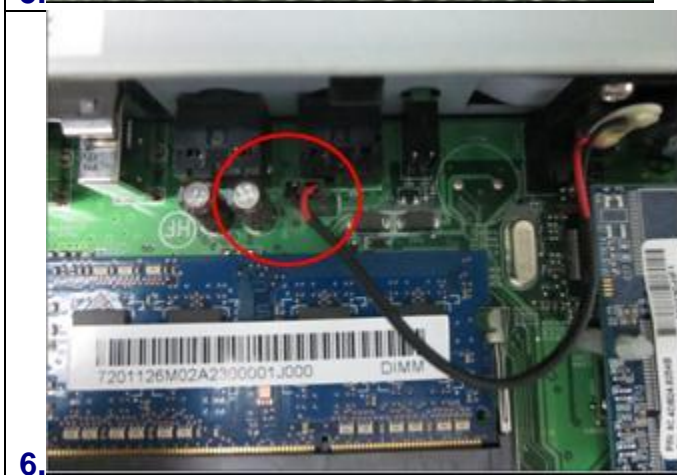
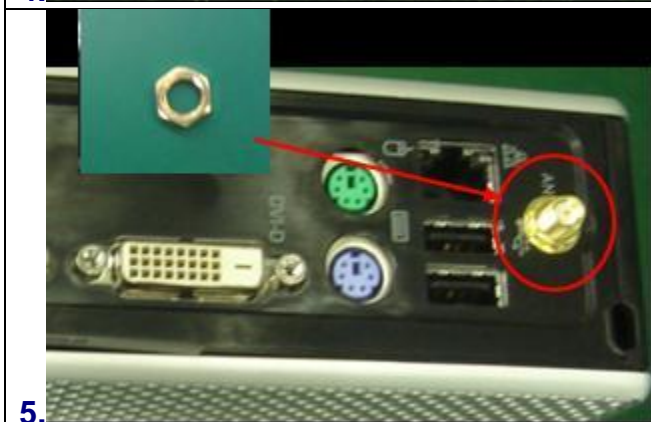


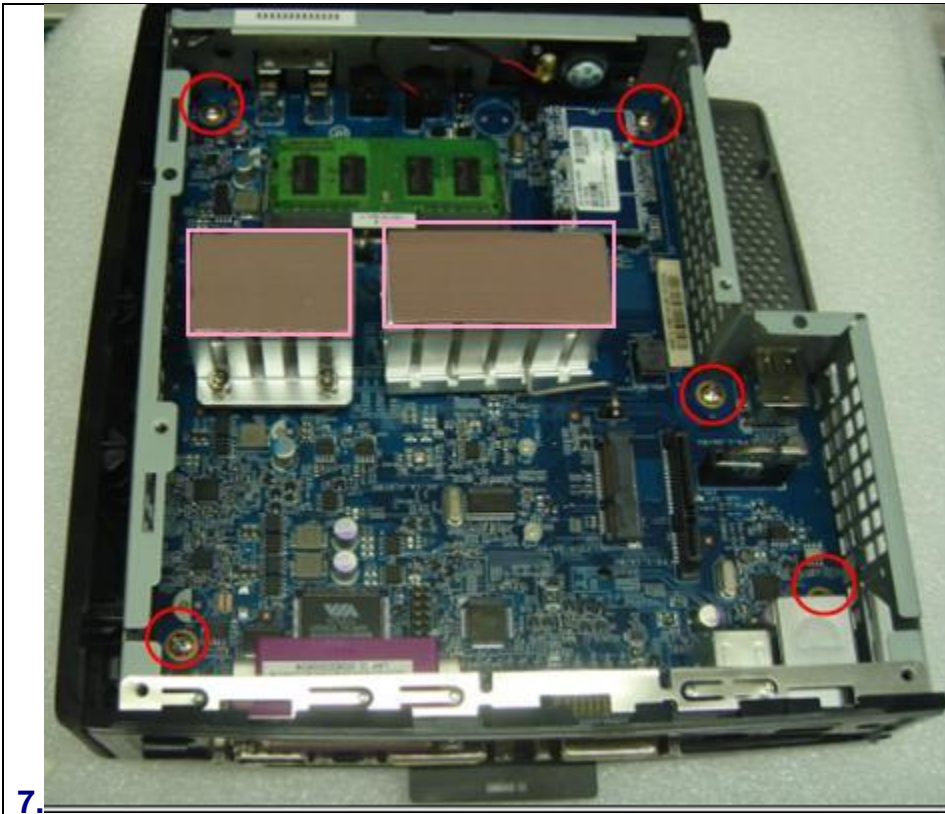
Follow the direction by arrow and push

2-1.









7.



8.

